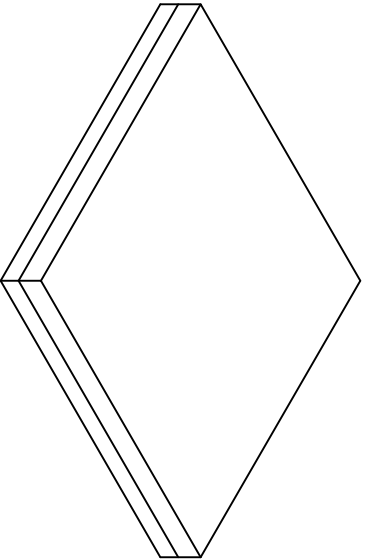


REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	N/A	INITIAL RELEASE	HLIM	HLIM	05/04/04
01	N/A	CHANGED THE BALL SIZE FROM 0.27mm TO 0.25mm	ETHONG	ETHONG	03/03/05



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC. #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC. #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 529.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 23 X 23.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.40mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Amkor Technology, Inc. Chandler, Arizona, USA Amkor Semiconductor, Inc., Seoul, Korea Amkor Technology Philippines, Inc. Cebu, Philippines		Amkor Technology ANAM Semiconductor	
DECIMAL X.X ±0.1 X.XX ±0.05 X.XXX ±0.030	ANGULAR ±1°			APPROVALS		TITLE	
INTERPRET DIM AND TOL. PER ASME Y14.5M - 1994		DATE		DESIGNED	04/30/04	PACKAGE OUTLINE - MAF, 23 X 23 MATRIX, 10.00mm X 10.00mm X 1.07mm, 0.70mm MOLD CAP, 0.25mm BALL, 0.40mm PITCH, LAMINATE SUBSTRATE, AAWW	
N/A		04/30/04		CHECKED	04/30/04	SIZE	SD NUMBER
N/A		04/30/04		PRODUCT MANAGER	04/30/04	N/A	N/A
N/A		05/04/04		RELEASED	05/04/04	STRIP DWG NUMBER/REV	PRG OUTLINE DWG NO.
N/A		05/04/04		JD/KIM	05/04/04	N/A	N/A
DO NOT SCALE DRAWING		SCALE		SHEET		1 OF 3	
		NONE		309194		REV	
						01	